



Material Content Data Sheet



Sales Product Name		BSC014NE2LSI		Issued		29. August 2013		
MA#		MA001015580						
Package		PG-TDSON-8-7		Weight*		118.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.687	0.58	0.58	5793	5793
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		319	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.85	31.89	318559	318974
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	379	379
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		737	
	plastics	epoxy resin	-	6.206	5.24		52353	
	inorganic material	silicondioxide	60676-86-0	37.410	31.56	36.87	315591	368681
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12246	12246
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1396	1396
solder	noble metal	silver	7440-22-4	0.026	0.02		215	
	non noble metal	tin	7440-31-5	0.020	0.02		172	
	non noble metal	lead	7439-92-1	0.975	0.82	0.86	8226	8613
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.55	9.56	95496	95621
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.81	18.84	188053	188297
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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